

# MM54HC125/MM74HC125 MM54HC126/MM74HC126 TRI-STATE® Quad Buffers

## **General Description**

These are general purpose TRI-STATE high speed non-inverting buffers utilizing advanced silicon-gate CMOS technology. They have high drive current outputs which enable high speed operation even when driving large bus capacitances. These circuits possess the low power dissipation of CMOS circuitry, yet have speeds comparable to low power Schottky TTL circuits. Both circuits are capable of driving up to 15 low power Schottky inputs.

The MM54HC125/MM74HC125 require the TRI-STATE control input C to be taken high to put the output into the high impedance condition, whereas the MM54HC126/ MM74HC126 require the control input to be low to put the output into high impedance.

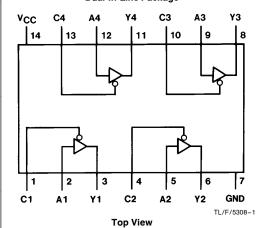
All inputs are protected from damage due to static discharge by diodes to V<sub>CC</sub> and ground.

### **Features**

- Typical propagation delay: 13 ns
- Wide operating voltage range: 2-6V
- Low input current: 1 µA maximum
- Low quiescent current: 80 µA maximum (74HC)
- Fanout of 15 LS-TTL loads

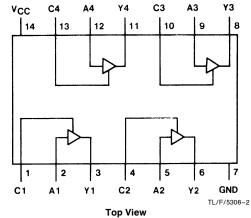
## **Connection Diagrams**

### **Dual-In-Line Package**



Order Number MM54HC125 or MM74HC125

### C4 ٧4 C3



**Dual-In-Line Package** 

Order Number MM54HC126 or MM74HC126

## **Truth Tables**

Inputs		Output		
Α	С	Y		
Н	L	Н		
L	L	L		
X	Н	Z		

Inputs Output Α C Н Н Н L Н Х 7

## Absolute Maximum Ratings (Notes 1 & 2) If Military/Aerospace specified devices are required,

please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (V<sub>CC</sub>) -0.5 to +7.0V DC Input Voltage (V<sub>IN</sub>) -1.5 to  $V_{\hbox{\footnotesize CC}}\!+1.5V$ DC Output Voltage (V<sub>OUT</sub>) -0.5 to  $V_{\hbox{\footnotesize CC}}\!+\!0.5V$ Clamp Diode Current (I<sub>IK</sub>, I<sub>OK</sub>)  $\pm$  20 mA DC Output Current, per pin (I<sub>OUT</sub>)  $\pm\,35~\text{mA}$ DC V<sub>CC</sub> or GND Current, per pin (I<sub>CC</sub>)  $\pm\,70~mA$ Storage Temperature Range (T<sub>STG</sub>) -65°C to +150°C

Power Dissipation (PD)

600 mW (Note 3) 500 mW S.O. Package only 260°C

Lead Temp. (T<sub>L</sub>) (Soldering 10 seconds)

Operating Conditions							
	Min	Max	Units				
Supply Voltage (V <sub>CC</sub> )	2	6	V				
DC Input or Output Voltage $(V_{IN}, V_{OUT})$	0	$V_{CC}$	V				
Operating Temp. Range (TA)							
MM74HC	-40	+85	°C				
MM54HC	-55	+125	°C				
Input Rise or Fall Times							
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns				
$V_{CC} = 4.5V$		500	ns				
$V_{CC} = 6.0V$		400	ns				

## **DC Electrical Characteristics** (Note 4)

Symbol	Parameter	Conditions	v <sub>cc</sub>	T <sub>A</sub> =25°C		74HC T <sub>A</sub> = -40 to 85°C	54HC T <sub>A</sub> = -55 to 125°C	Units
				Тур		Guaranteed		
V <sub>IH</sub>	Minimum High Level Input Voltage		2.0V 4.5V 6.0V		1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V V V
V <sub>IL</sub>	Maximum Low Level Input Voltage**		2.0V 4.5V 6.0V		0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V V V
V <sub>OH</sub>	Minimum High Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \mu A$	2.0V 4.5V 6.0V	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 6.0 \text{ mA}$ $ I_{OUT}  \le 7.8 \text{ mA}$	4.5V 6.0V	4.2 5.7	3.98 5.48	3.84 5.34	3.7 5.2	V V
V <sub>OL</sub>	Maximum Low Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \mu A$	2.0V 4.5V 6.0V	0 0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V V V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 6.0 \text{ mA}$ $ I_{OUT}  \le 7.8 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	0.4 0.4	V V
l <sub>OZ</sub>	Maximum TRI-STATE Output Leakage Current	$V_{IN} = V_{IH}$ or $V_{IL}$ $V_{OUT} = V_{CC}$ or GND $C_n = Disabled$	6.0V		±0.5	±5	±10	μΑ
I <sub>IN</sub>	Maximum Input Current	V <sub>IN</sub> =V <sub>CC</sub> or GND	6.0V		±0.1	±1.0	±1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$	6.0V		8.0	80	160	μΑ

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 3: Power Dissipation temperature derating — plastic "N" package: -12 mW/°C from 65°C to 85°C; ceramic "J" package: -12 mW/°C from 100°C to 125°C.

Note 4: For a power supply of 5V  $\pm$ 10% the worst case output voltages ( $V_{OH}$ , and  $V_{OL}$ ) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case V<sub>IH</sub> and V<sub>IL</sub> occur at V<sub>CC</sub>=5.5V and 4.5V respectively. (The V<sub>IH</sub> value at 5.5V is 3.85V.) The worst case leakage current (I<sub>IN</sub>, I<sub>CC</sub>, and  $I_{\mbox{OZ}}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

<sup>\*\*</sup>V<sub>IL</sub> limits are currently tested at 20% of V<sub>CC</sub>. The above V<sub>IL</sub> specification (30% of V<sub>CC</sub>) will be implemented no later than Q1, CY'89.

# AC Electrical Characteristics $v_{CC} = 5 \text{V}, T_A = 25 ^{\circ}\text{C}, C_L = 45 \text{ pF}, t_r = t_f = 6 \text{ ns}$

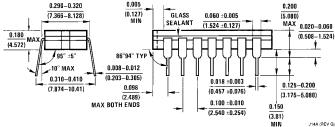
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay Time		13	18	ns
t <sub>PZH</sub>	Maximum Output Enable Time to High Level	$R_L = 1 k\Omega$	13	25	ns
t <sub>PHZ</sub>	Maximum Output Disable Time from High Level	$R_L = 1 k\Omega$ $C_L = 5 pF$	17	25	ns
t <sub>PZL</sub>	Maximum Output Enable Time to Low Level	$R_L = 1 k\Omega$	18	25	ns
t <sub>PLZ</sub>	Maximum Output Disable Time from Low Level	$R_L = 1 k\Omega$ $C_L = 5 pF$	13	25	ns

# $\textbf{AC Electrical Characteristics} \ \ V_{CC} = 2.0 \ \ \text{to 6.0V}, \ C_L = 50 \ \ \text{pF}, \ t_f = t_f = 6 \ \text{ns (unless otherwise specified)}$

	Parameter	Conditions	v <sub>cc</sub>	Temperature °C				
Symbol				54HC/74HC T <sub>A</sub> = 25°C		74HC -40 to 85°C	54HC -55 to 125°C	Units
				Тур		Guaranteed L	imits.	
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation		2.0V	40	100	125	150	ns
	Delay Time		4.5V	14	20	25	30	ns
			6.0V	12	17	21	25	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation	C <sub>L</sub> =150 pF	2.0V	35	130	163	195	ns
	Delay Time		4.5V	14	26	33	39	ns
			6.0V	12	22	28	33	ns
t <sub>PZH</sub> , t <sub>PZL</sub>	Maximum Output	$R_L = 1 k\Omega$	2.0V	25	125	156	188	ns
	Enable Time		4.5V	14	25	31	38	ns
			6.0V	12	21	26	31	ns
t <sub>PHZ</sub> , t <sub>PLZ</sub>	Maximum Output	$R_L = 1 k\Omega$	2.0V	25	125	156	188	ns
	Disable Time		4.5V	14	25	31	38	ns
			6.0V	12	21	26	31	ns
$t_{PZL}$ , $t_{PZH}$	Maximum Output	C <sub>L</sub> = 150 pF	2.0V	35	140	175	210	ns
	Enable Time	$R_L = 1 k\Omega$	4.5V	15	28	35	42	ns
			6.0V	13	24	30	36	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output	C <sub>L</sub> =50 pF	2.0V	30	60	75	90	ns
	Rise and Fall Time		4.5V	7	12	15	18	ns
			6.0V	6	10	13	15	ns
C <sub>IN</sub>	Input Capacitance			5	10	10	10	pF
C <sub>OUT</sub>	Output Capacitance Outputs			15	20	20	20	pF
C <sub>PD</sub>	Power Dissipation	(per gate)						
. =	Capacitance (Note 5)	Enabled		45				pF
		Disabled		6				pF

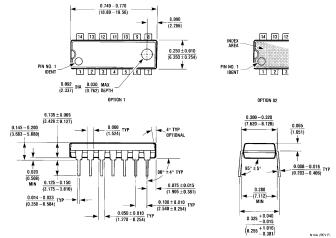
Note 5:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} \ V_{CC} \ f + I_{CC} \ V_{CC}$ .

### Physical Dimensions inches (millimeters) 0.785 (19.939) MAX [14] [13] [12] [11] [10] [9] [8] 0.025 (0.635) RAD 0.220-0.310 (5.588-7.874)



1 2 3 4 5 6 7

Order Number MM54HC125J, MM54HC126J, MM74HC125J, or MM74HC126J NS Package J14A



Order Number MM74HC125N, or MM74HC126N NS Package N14A

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National Semiconductor

National Semiconducto Corporation 1111 West Bardin Road Arlington, TX 76017 Tel: 1(800) 272-9959 Fax: 1(800) 737-7018

**National Semiconductor** 

Europe Fax: (+49) 0-180-530 85 86 Fax: (+49) U-18U-35U oo oo Email: onjwege tevm2.nsc.com Deutsch Tel: (+49) 0-180-530 85 85 English Tei: (+49) 0-180-532 78 32 Français Tel: (+49) 0-180-532 93 58 Italiano Tel: (+49) 0-180-534 16 80 National Semiconductor Hong Kong Ltd.
13th Floor, Straight Block,
Ocean Centre, 5 Canton Rd.

Tsimshatsui, Kowloon Hong Kong Tel: (852) 2737-1600 Fax: (852) 2736-9960

National Semiconductor

Japan Ltd.
Tel: 81-043-299-2309
Fax: 81-043-299-2408